TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOSIII)

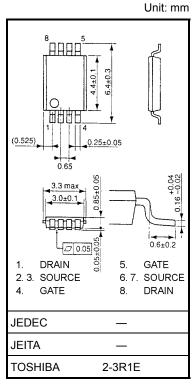
TPCS8204

Lithium Ion Battery Applications Notebook PC Applications Portable Equipment Applications

- Small footprint due to small and thin package
- Low drain-source ON resistance: R_{DS} (ON) = 13 m Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 15 S$ (typ.)
- Low leakage current: $I_{DSS} = 10 \mu A \text{ (max) (V}_{DS} = 20 \text{ V)}$
- Enhancement mode: $V_{th} = 0.5 \sim 1.2 \text{ V}$ ($V_{DS} = 10 \text{ V}$, $I_D = 200 \mu A$)

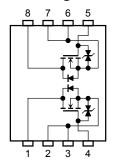
Absolute Maximum Ratings (Ta = 25°C)

Char	acteristics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	20	V	
Drain-gate voltag	ge (R _{GS} = 20 kΩ)	V_{DGR}	20	V	
Gate-source volt	age	V _{GSS}	±12	V	
Drain current	DC (Note 1)	I _D	6	Α	
Diain current	Pulse (Note 1)	I _{DP}	24	A	
Drain power dissipation	Single-device operation (Note 3a)	P _{D (1)}	1.1		
(t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.75	W	
Drain power dissipation	Single-device operation (Note 3a)	P _{D (1)}	0.6		
(t = 10 s) (Note 2b)	Single-device value at dual operation (Note 3b)	P _{D (2)}		W	
Single pulse ava	lanche energy (Note 4)	E _{AS}	46.8	mJ	
Avalanche curre	nt	I _{AR}	6	Α	
Repetitive avalar Single-device va	nche energy lue at dual operation (Note 2a, 3b, 5)	E _{AR}	0.075	mJ	
Channel tempera	ature	T _{ch}	150	°C	
Storage tempera	ture range	T _{stg}	−55 ~ 150	°C	



Weight: 0.035 g (typ.)

Circuit Configuration



Note: (Note 1), (Note 2), (Note 3), (Note 4) and (Note 5): See the next page.

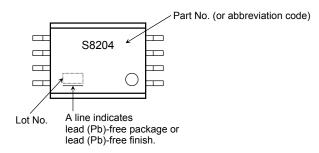
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

This transistor is an electrostatic-sensitive device. Please handle with caution.

Thermal Characteristics

Characteristics	Symbol	Max	Unit		
	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	114		
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	R _{th} (ch-a) (2)	167	°C/W	
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	208		
(t = 10 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R _{th} (ch-a) (2)	357	°C/W	

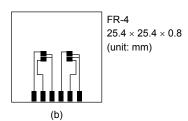
Marking (Note 6)



Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2:

- a) Device mounted on a glass-epoxy board (a)
 - FR-4 25.4 × 25.4 × 0.8 (unit: mm)
- b) Device mounted on a glass-epoxy board (b)



Note 3:

- a) The power dissipation and thermal resistance values are shown for a single device.
 (During single-device operation, power is only applied to one device.)
- b) The power dissipation and thermal resistance values are shown for a single device. (During dual operation, power is evenly applied to both devices.)
- Note 4: $V_{DD}=16~V,~T_{ch}=25^{\circ}C$ (initial), $L=1.0~mH,~R_{G}=25~\Omega,~I_{AR}=6~A$
- Note 5: Repetitive rating: pulse width limited by maximum channel temperature
- Note 6: on lower left of the marking indicates Pin 1.



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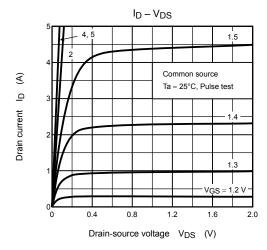


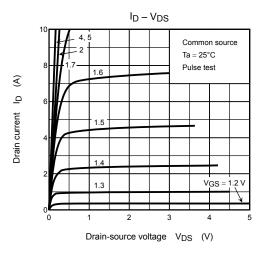
Electrical Characteristics (Ta = 25°C)

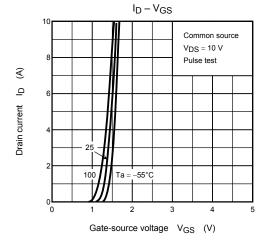
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cui	rrent	I _{GSS}	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Drain cut-OFF cu	ırrent	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V	_	_	10	μА
Drain-source bre	akdown voltage	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	20		_	V
Dialii-source bre	akdown voltage	V _{(BR) DSX}	$I_D = 10 \text{ mA}, V_{GS} = -12 \text{ V}$	8	_	_	٧
Gate threshold v	oltage	V _{th}	$V_{DS}=10~V,~I_D=200~\mu\text{A}$	0.5 — 1.2		٧	
			$V_{GS} = 2.0 \text{ V}, I_D = 4.2 \text{ A}$		24	35	mΩ
Drain-source ON	resistance	R _{DS} (ON)	$V_{GS} = 2.5 \text{ V}, I_D = 4.2 \text{ A}$	_	18	22	
			$V_{GS} = 4.0 \text{ V}, I_D = 4.8 \text{ A}$	_	13	17	
Forward transfer admittance		Y _{fs}	$V_{DS} = 10 \text{ V}, I_D = 3.0 \text{ A}$	7.5	15	_	S
Input capacitance		C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	2160	_	pF
Reverse transfer capacitance		C _{rss}		_	210	_	
Output capacitance		Coss		_	230	_	
Switching time	Rise time	t _r	Act 2 A A A A A A A A A A A A A A A A A A		5	_	
	Turn-ON time	t _{on}			13	_	- ns
	Fall time	t _f			10	_	
	Turn-OFF time	t _{off}	$V_{DD} \simeq 10 \text{ V}$ Duty \leq 1%, $t_W = 10 \mu\text{s}$		53		
Total gate charge (gate-source plus gate-drain)		Qg		_	22	_	
Gate-source charge 1		Q _{gs1}	$V_{DD} \simeq 16 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 6 \text{ A}$	_	4	_	nC
Gate-drain ("mille	er") charge	Q _{gd}		_	5	_	

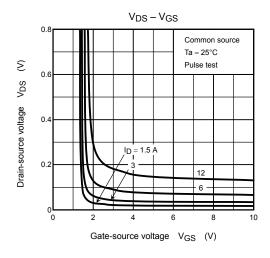
Source-Drain Ratings and Characteristics (Ta = 25°C)

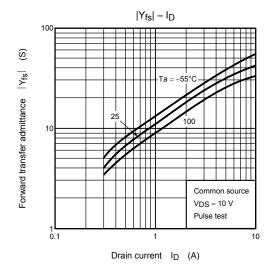
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	_	_	_	24	Α
Forward voltage (diode)		V _{DSF}	$I_{DR} = 6 A$, $V_{GS} = 0 V$	_	_	-1.2	V

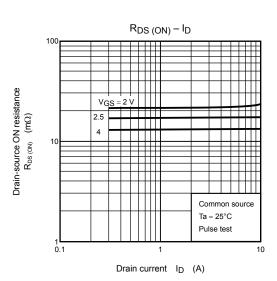




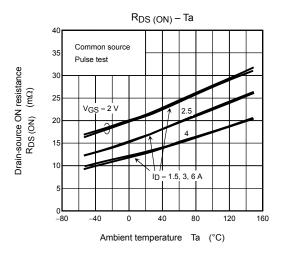


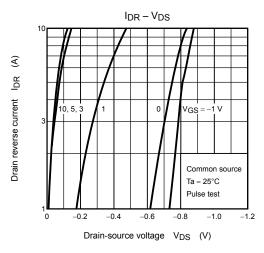


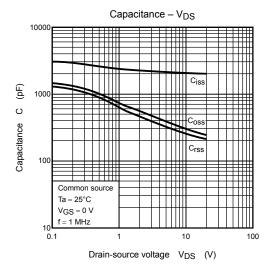


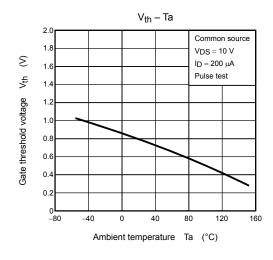


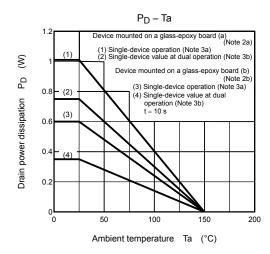
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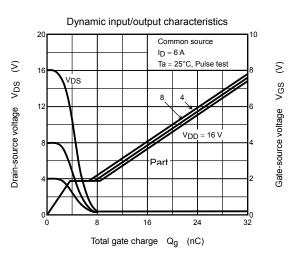




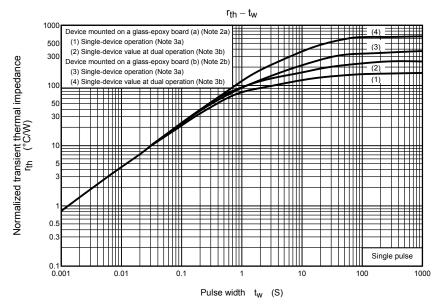




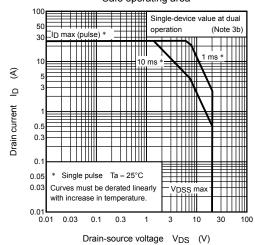




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